

30V N-Channel Enhancement-Mode Mosfet

30V N 沟道增强型 MOS 管

**VDS= 30V**

**RDS(ON), Vgs@10.0V, Ids@12.0A = 9.0mΩ**

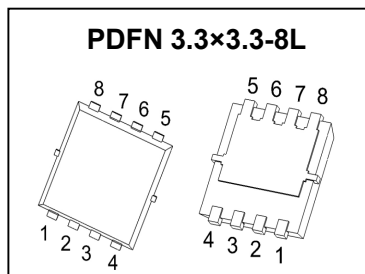
**RDS(ON), Vgs@4.5V, Ids@10.0A = 15.0mΩ**

## Features 特性

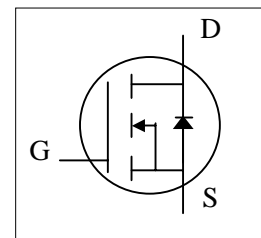
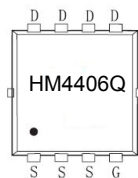
Advanced trench process technology 高级的加工技术

High Density Cell Design For Ultra Low On-Resistance 极低的导通电阻高密度的单元设计

High Power and Current handling capability 大功率高电流



## Marking



Maximum Ratings and Thermal Characteristics (TA = 25 °C unless otherwise noted) 25 °C 极限参数和热特性

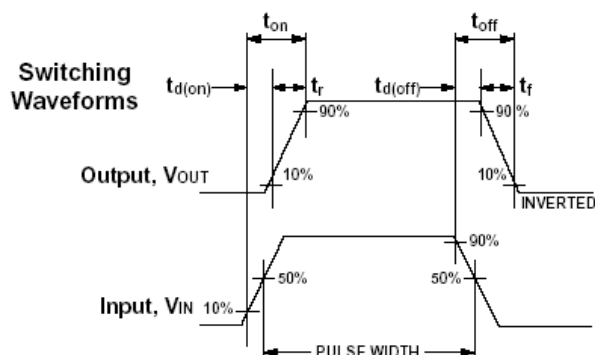
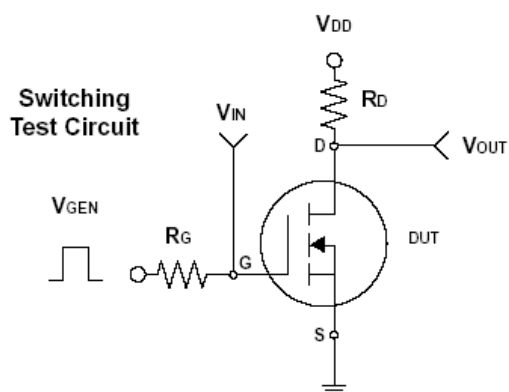
Parameter 极限参数	Symbol 符号	Limit 范围	Unit 单位
Drain-Source Voltage 漏源电压	V <sub>DS</sub>	30	V
Gate-Source Voltage 栅源电压	V <sub>GS</sub>	± 20	
Continuous Drain Current 连续漏极电流	I <sub>D</sub>	30	A
Pulsed Drain Current 脉冲漏极电流	I <sub>DM</sub>	100	
Maximum Power Dissipation 最大耗散功率	P <sub>D</sub>	1.5	W
		0.8	
Operating Junction and Storage Temperature Range 使用及储存温度	T <sub>J</sub> , T <sub>stg</sub>	-55 to 150	°C
Junction-to-Ambient Thermal Resistance (PCB mounted) 结环热阻	R <sub>θJA</sub>	83.5	°C/W

Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for drain 6 cm<sup>2</sup>, t ≤ 5 s.

ELECTRICAL CHARACTERISTICS 一般电气特性

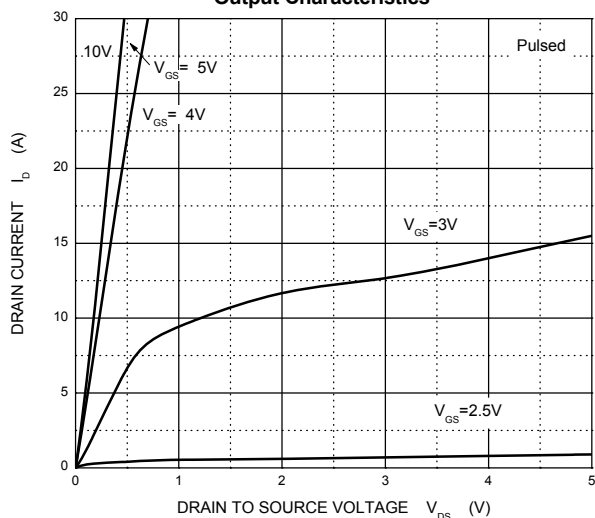
Parameter 参数	符号	Test Condition 测试条件	最小值	典型值	最大值	单位
Static 静态参数						
Drain-Source Breakdown Voltage 漏源击穿电压	BV <sub>DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250uA	30			V
Drain-Source On-State Resistance 漏源导通电阻	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10.0 V, I <sub>D</sub> = 12.0A		7.0	9.0	mΩ
Drain-Source On-State Resistance 漏源导通电阻	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 10.0A		9.0	15.0	
Gate Threshold Voltage 开启电压	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> = 250uA	1.0	1.6	3.0	V
Zero Gate Voltage Drain Current 零栅压漏极电流	I <sub>DSS</sub>	V <sub>DS</sub> = 24V, V <sub>GS</sub> = 0V			1	uA
Gate Body Leakage 漏极短路时截止栅电流	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V			±100	nA
Forward Transconductance 正向跨导	g <sub>fs</sub>	V <sub>DS</sub> =5.0 V, I <sub>D</sub> = 20A		15		S
Dynamic 动态参数						
Total Gate Charge 栅极总电荷	Q <sub>g</sub>	V <sub>DS</sub> = 15V, I <sub>D</sub> =12.0A V <sub>GS</sub> = 4.5V		9.3		nC
Gate-Source Charge 栅-源极电荷	Q <sub>gs</sub>			2.4		
Gate-Drain Charge 栅-漏极电荷	Q <sub>gd</sub>			3.8		
Turn-On Delay Time 导通延迟时间	t <sub>d(on)</sub>	V <sub>DD</sub> = 15 V, R <sub>G</sub> = 6Ω I <sub>D</sub> = 12 A , V <sub>GS</sub> = 4.5V		10.1		ns
Turn-On Rise Time 导通上升时间	t <sub>r</sub>			12.3		
Turn-Off Delay Time 关断延迟时间	t <sub>d(off)</sub>			30.4		
Turn-Off Fall Time 关断下降时间	t <sub>f</sub>			6.5		
Input Capacitance 输入电容	C <sub>iss</sub>	V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 0V f = 1.0 MHz		1165		pF
Output Capacitance 输出电容	C <sub>oss</sub>			172		
Reverse Transfer Capacitance 反向传输电容	C <sub>rss</sub>			89.5		
Source-Drain Diode 源漏二极管参数						
Max. Diode Forward Current 最大正向电流	I <sub>S</sub>				20	A
Diode Forward Voltage 正向电压	V <sub>SD</sub>	I <sub>S</sub> = 10 A, V <sub>GS</sub> = 0V			1.2	V

Note: Pulse test: pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$  注意: 脉冲测试: 脉冲宽度  $\leq 300\mu s$  死区  $\leq 2\%$

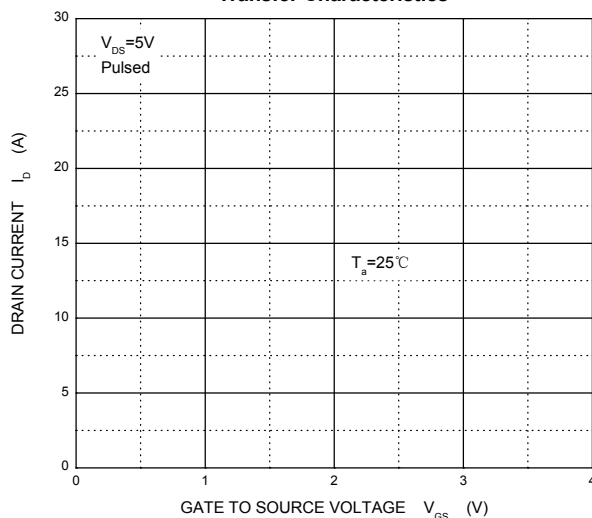


## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

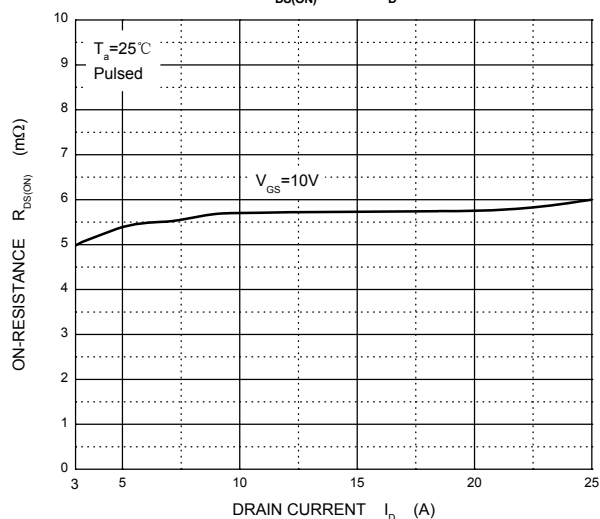
Output Characteristics



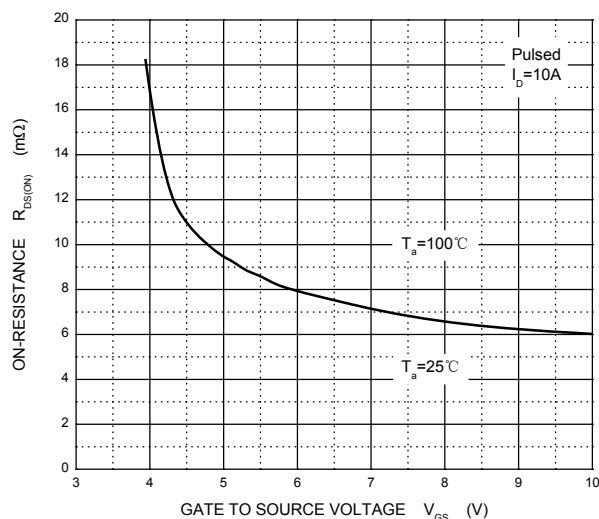
Transfer Characteristics



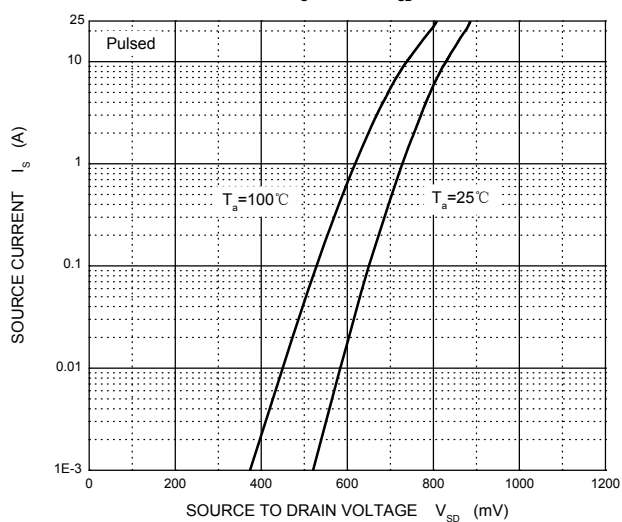
$R_{DS(ON)}$  —  $I_D$



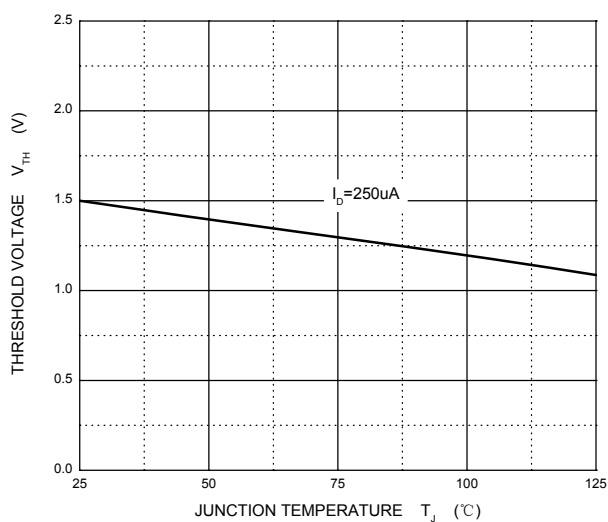
$R_{DS(ON)}$  —  $V_{GS}$



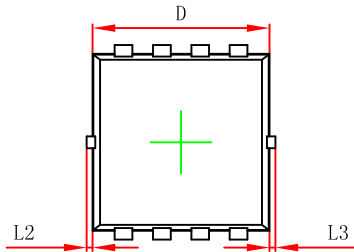
$I_S$  —  $V_{SD}$



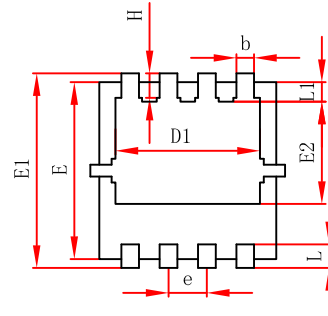
Threshold Voltage



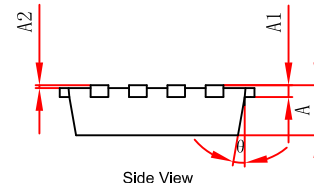
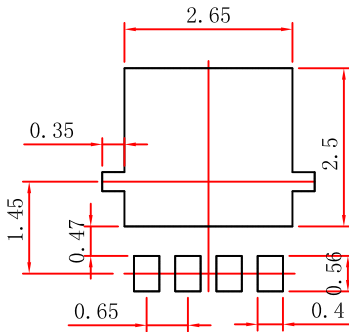
PDFN 3.3\*3.3-8L Package Outline Dimensions



Top View  
 [顶视图]



Bottom View  
 [背视图]



Side View  
 [侧视图]

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.650	0.850	0.026	0.033
A1	0.152 REF.		0.006 REF.	
A2	0~0.05		0~0.002	
D	2.900	3.100	0.114	0.122
D1	2.300	2.600	0.091	0.102
E	2.900	3.100	0.114	0.122
E1	3.150	3.450	0.124	0.136
E2	1.535	1.935	0.060	0.076
b	0.200	0.400	0.008	0.016
e	0.550	0.750	0.022	0.030
L	0.300	0.500	0.012	0.020
L1	0.180	0.480	0.007	0.019
L2	0~0.100		0~0.004	
L3	0~0.100		0~0.004	
H	0.315	0.515	0.012	0.020
θ	9°	13°	9°	13°